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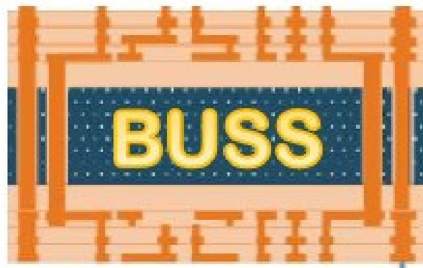

Second IEEE Advanced Substrate Conference

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Build-Up Substrate Symposium

May 8-9, 2025 SEMI Headquarters, Silicon Valley, CA USA

BUSS'25 *is an* ***in-person event****. Register at* attend.ieee.org/buss

Volume manufacturers of build-up substrates are entirely based in Asia, leaving a desert in the US. However, there are multiple activities starting up in the US, and this is why a gathering of the US players is important. This symposium is geared for all those involved in the supply chain of build-up substrates in the US, as well as current and potential users. This Symposium is an opportunity for all build-up substrate players to meet, network and cohesively work with funding agencies who will be invited to this symposium to focus on onshoring build-up substrate production and utilization.

General Chair: Habib Hichri, Ajinomoto

Program Chair: Annette Teng, NY Creates

Omar Bchir Qualcomm - Keynote: **Next Generation Organic Substrate Technology**

Jan Vardaman, TechSearch Int'l Panel: **Tech R&D Centers of Excellence**

Yuya Suzuki, Taiyo America: **Dry-film Solder Resist Materials for High Density IC Substrates**

Hikaru Mizuno, JSR Micro: **Advanced Photo-imageable Dielectric Film for Sub-5-micron Patterning for Next Generation Build-up Layer**

Yoshihiro Inoue, Nikko Materials: **The Latest Vacuum Lamination Challenges and Technology Development**

Debendra Das Sharma, Intel: **Open Chiplet Innovation with Vertical and Planar Connectivity**

Steven Verhaverbeke, Applied Materials: **Wafer-Level Si Core Substrates – Third Leg of the NAPMP Substrates Program**

Shiro Tatsumi, Ajinomoto: **Advanced Insulation Material for High Perform-ance Packages**

Vern Stygar, AGC: **Glass Compositions for Data Centers, AI, and Quantum Computing**

John Damoulakis, Cadence Design Systems: **Complexity Handling of Integrated Circuit Design Using AI-based EDA Technology with Smart Substrates**

Venky Sundaram, 3D System Scaling: Panel: **What is needed to reduce the Gap between US and Overseas Substrate Manufacturing?**

and more!

Sessions on:

Substrate Challenges for Chiplet Integration
Materials for Substrates
Emerging Substrate Technologies
Substrate Equipment and Technologies
Design Integrations
Metrology

Plus presentations by **AMD, DNP, Shinko, Ibiden, Absolics, Amkor, MKS, Broadcom, Google, Shahab, Onto, and more**
(subject to change)

For further information, go to attend.ieee.org/buss

Registration is now open!
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